

ALMENEXT Sales Material

ALMEX TECHNOLOGIES Inc.

Sales group

August,2021





Advanced Vertical Continuous Plating system (VCP)

High speed applications & Fine L/S applications

ALMEX TECHNOLOGIES 2021



ALMENEXT History

1st Generation 1998 - 2000

> Release of preliminary ALMEX VCP model

2nd Generation 2000 - 2017

- Mini-environmental design for dust reduction
- Provision of SAP plating capability

3rd Generation 2017 - Today

Provision of leading edge capability for SAP & MSAP products

The latest generation - ALMENEXT

To provide more sophisticated and highperformance functions



Market Requirements

High speed data transmission applications

- Uniform copper plating thickness (For tight impedance control)
- > Uniform trace width (For good yield)
- > Fine L/S FC-BGA applications(8µm minimum)

AiP / AoP applications

➤ Asymmetric copper balance between front and back of the panel

Mobile applications

> To be light, thin, short and small



Causes of Cu thickness deviation

Development Focus

- > Current concentration at specific area of panel
- > Unexpected current flow to another side
- ➤ Non-optimized current profile at rectifier transition zone
- Warpage of panel
 - √ Non-optimized fixture design
 - √ Bad panel loading in fixture

The description for the product design, specifications, data may vary due to further development activities without prior notice. Thank you for your understanding that the data in this material may vary due to customer's test conditions.

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Technical innovations

New current supply system

- Complete current isolation between front and back side of panel
- Anode contact optimization
- > Full-flat busbar

New fixture design

New design of sacrificial plates
(To improve current concentration at panel edge)

Optimum current profile

 Sophisticated current control, especially for soft start /soft end(*) profile (To optimize current profile at rectifier transition)

(*)ramp up and ramp down



Manufacturing policy for accurate equipment

Commitment to Material Quality

Made-in-Japan Material/Parts (or equivalent) are proactively used for important parts that determine plating accuracy, MTBF and equipment life

Commitment to Manufacturing

- Cutting edge NC machines are used to keep accuracy
- > Certification system for key operations

Commitment to Inspection

➤ In-house developed inspection/measurement tools are used to assure assembly accuracy



Uniformity

ALMENEXT innovations provide unprecedented uniformity

60% variety improvement compared to current models (*)

Measurement condition

Panel size : 510 mm x 610 mm

Current density : 2.0 ASD Plating thickness : 20 µm

(*)Data of inhouse experiments (not assured)

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Uniformity inhouse data





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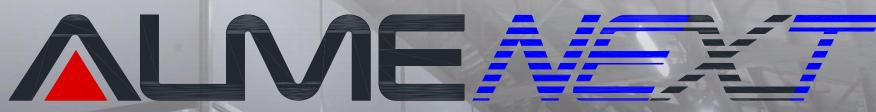
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Benefits for customers

- ✓ Improve product characteristics
- ✓ May increase the number of product units per panel
- ✓ Improve Yield
- ✓ Less inspection & measurement
- ✓ Easier process control
- ✓ Process step reduction



TM

Prototype equipment:

Available in ALMEX TECHNOLOGIES (ready for customer experiments)

Release schedule

1st Product shipment:

Planning in 2022 Q3

Start of sales activities:

2021 October